Advanced Packaging Update:
Market and Technology Trends

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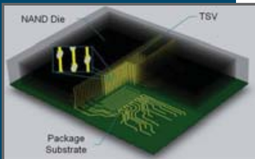

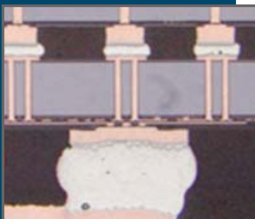

This issue of the Advanced Packaging Update features special coverage of outsourced assembly and test (OSAT) financials, including a discussion of merger and acquisition activities. An update on developments in large area fan-out wafer level package (FO-WLP) panel production is included. A section on trends in packaging and assembly for memory covers new developments in DRAM and Flash memory. The latest trends in high-performance computing are presented with a forecast for silicon interposers and a discussion of alternatives moving into production.

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